

Denistat Z 20G 04 Y

PPA/PA66 resin, 20% glass fiber reinforced, semiconductive
for injection moulding



PROPERTY	CONDITIONS	NORMS	UNITS	VALUE
PHYSICAL PROPERTIES				
Density	-	ISO-1183	g/cm ³	1,40
Linear Mould Shrinkage	-	ASTM D-955	%	0,3
Trasversal Mould Shrinkage	-	ASTM D-955	%	0,7
THERMAL PROPERTIES				
Heat Distortion Temperature	HDT A (1,80 MPa)	ASTM D-648	°C	257
Long Term Temperature	-	Internal Method	°C	140
MECHANICAL PROPERTIES				
Impact Strength Izod Notched	23 °C	ISO-180/A	kJ/m ²	8
Impact Strength Izod Unnotched	23 °C	ISO-180/U	kJ/m ²	40
Tensile Strength at Break	23 °C	ISO-527/1-2	MPa	150
Elongation at Break	23 °C	ISO-527/1-2	%	1,4
Tensile Modulus	23 °C	ISO-527/1-2	MPa	16000
ELECTRICAL PROPERTIES				
Surface Resistivity	-	ASTM D257	Ohm	10 ⁴